

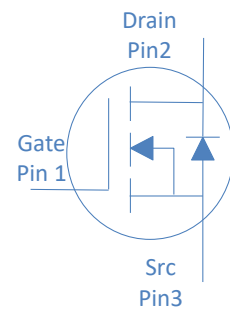
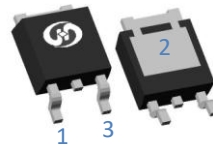
**65V N-Ch Power MOSFET**
**Feature**

- ◇ High Speed Power Switching
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

$V_{DS}$	65	V
$R_{DS(on),typ}$	2.6	m $\Omega$
$I_D$ (Silicon Limited)	160	A
$I_D$ (Package Limited)	120	A

**Application**

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial


**TO-252**


Part Number	Package	Marking
HGD028NE6A	TO-252	GD028NE6A

**Absolute Maximum Ratings at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ\text{C}$	160	A
		$T_C=100^\circ\text{C}$	113	
		$T_C=25^\circ\text{C}$	120	
Continuous Drain Current (Package Limited)			120	
Drain to Source Voltage	$V_{DS}$	-	65	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	400	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.1\text{mH}, T_C=25^\circ\text{C}$	80	mJ
Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	150	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	$^\circ\text{C}$

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	46	$^\circ\text{C/W}$
Thermal Resistance Junction-Case	$R_{\theta JC}$	1	$^\circ\text{C/W}$

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	65	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0	2.6	4.0	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS}=0V, V_{DS}=60V, T_j=25^\circ\text{C}$	-	-	1	$\mu A$
		$V_{GS}=0V, V_{DS}=60V, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	2.6	3.1	$m\Omega$
Transconductance	$g_{fs}$	$V_{DS}=5V, I_D=20A$	-	66	-	S
Gate Resistance	$R_G$	$V_{GS}=0V, V_{DS}$ Open, $f=1\text{MHz}$	-	1.25	-	$\Omega$

**Dynamic Characteristics**

Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=30V, f=1\text{MHz}$	-	4348	-	pF
Output Capacitance	$C_{oss}$		-	1501	-	
Reverse Transfer Capacitance	$C_{rss}$		-	92	-	
Total Gate Charge	$Q_g(10V)$	$V_{DD}=30V, I_D=20A, V_{GS}=10V$	-	66	-	nC
Gate to Source Charge	$Q_{gs}$		-	16	-	
Gate to Drain (Miller) Charge	$Q_{gd}$		-	16	-	
Turn on Delay Time	$t_{d(on)}$	$V_{DD}=30V, I_D=20A, V_{GS}=10V, R_G=10\Omega,$	-	15	-	ns
Rise time	$t_r$		-	12	-	
Turn off Delay Time	$t_{d(off)}$		-	52	-	
Fall Time	$t_f$		-	19	-	

**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_F=20A$	-	0.9	1.2	V
Reverse Recovery Time	$t_{rr}$	$V_R=30V, I_F=20A, di_F/dt=100A/\mu s$	-	50	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	50	-	nC

Fig 1. Typical Output Characteristics

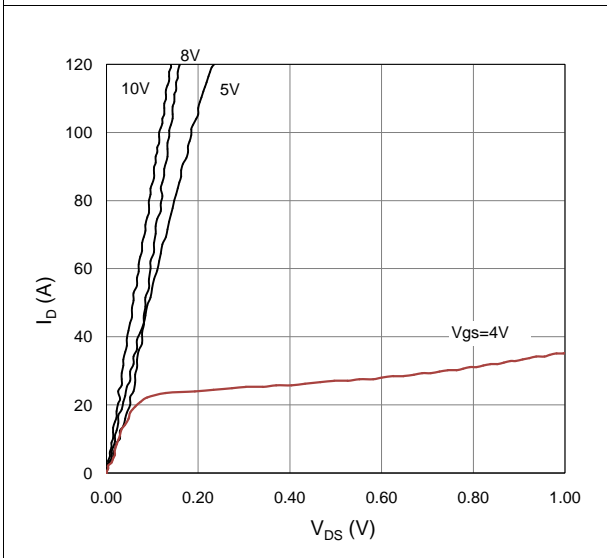


Figure 2. On-Resistance vs. Gate-Source Voltage

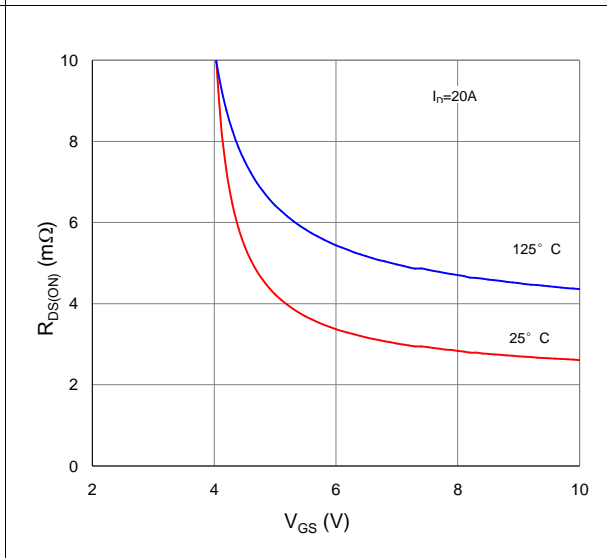


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

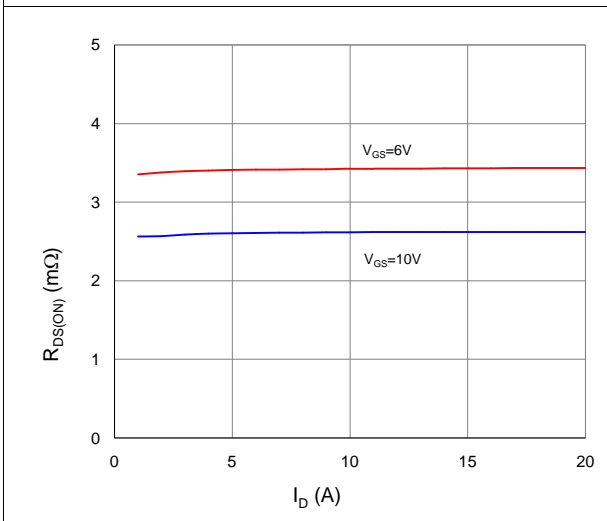


Figure 4. Normalized On-Resistance vs. Junction Temperature

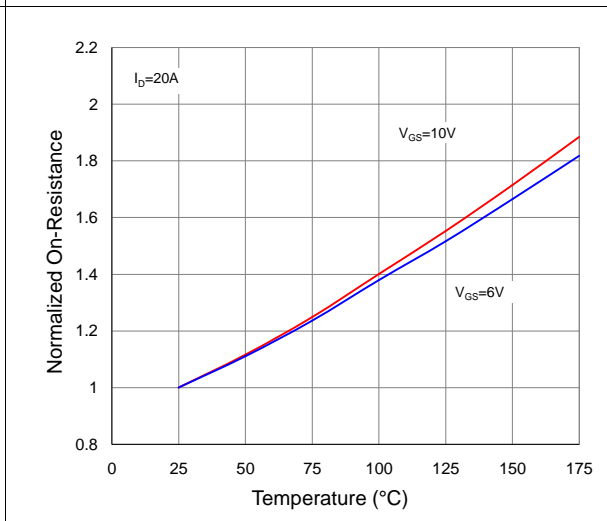


Figure 5. Typical Transfer Characteristics

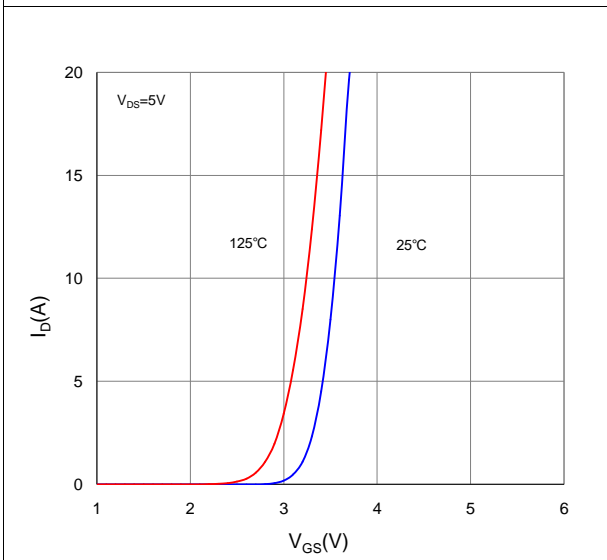


Figure 6. Typical Source-Drain Diode Forward Voltage

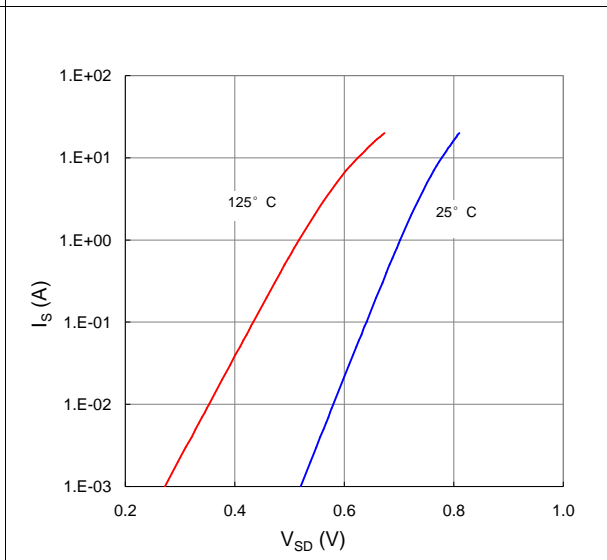


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

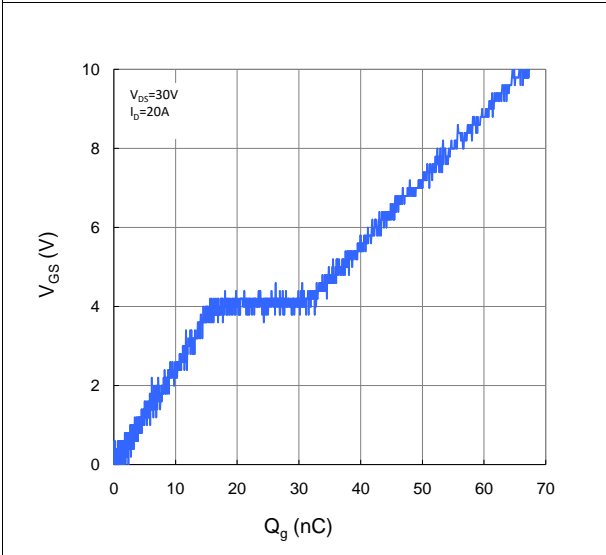


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

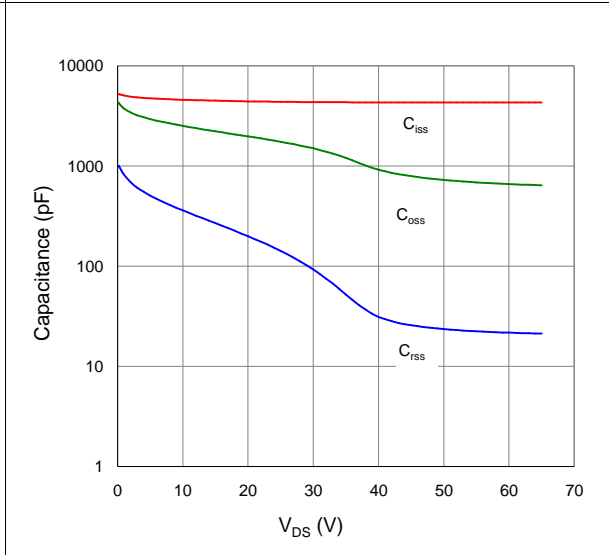


Figure 9. Maximum Safe Operating Area

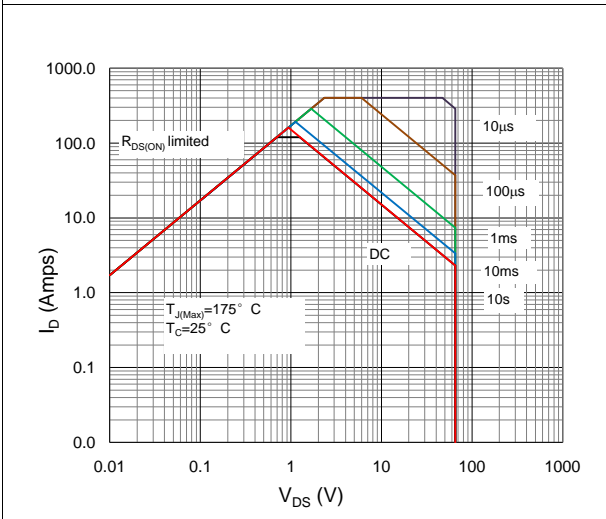


Figure 10. Maximum Drain Current vs. Case Temperature

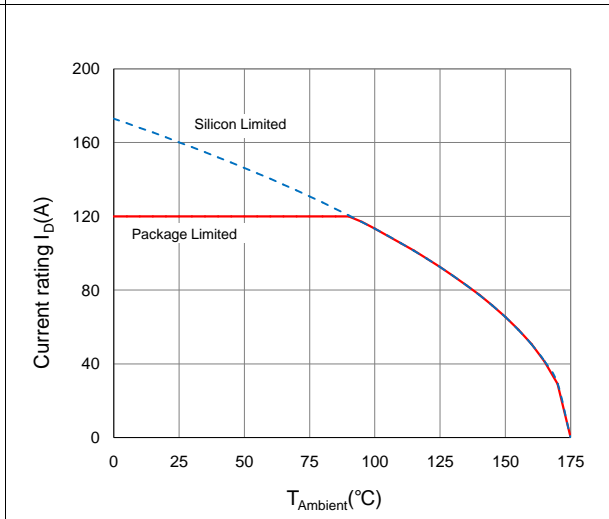
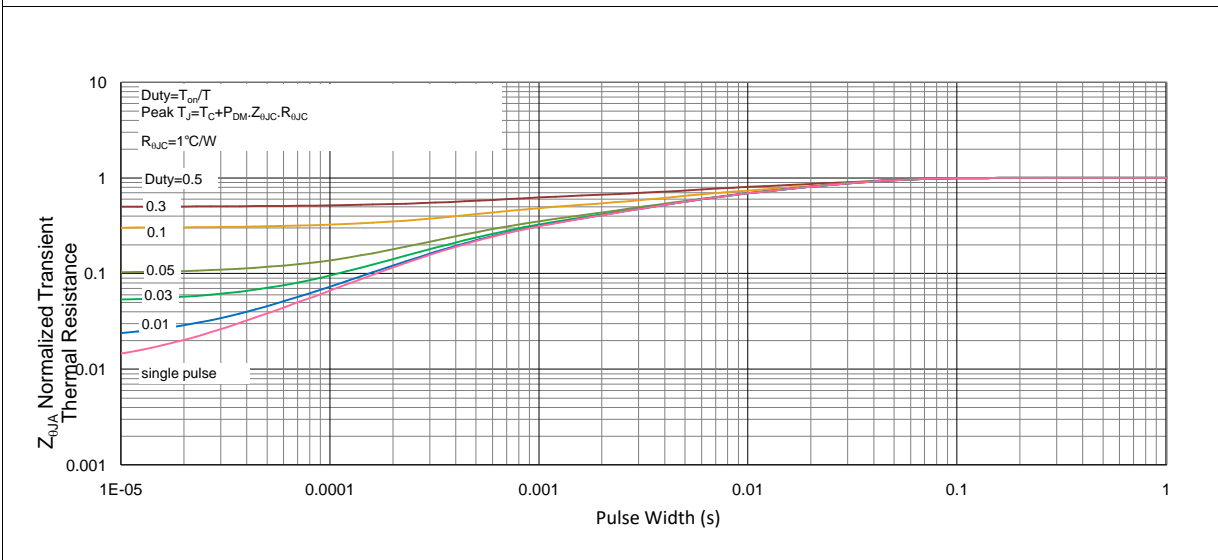
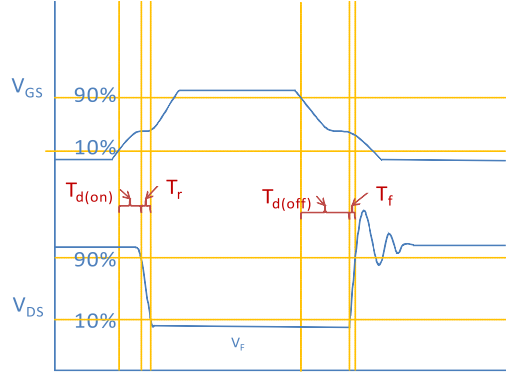
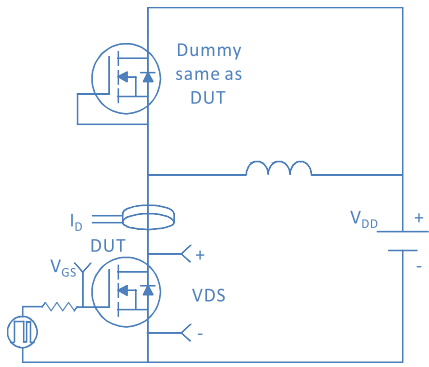


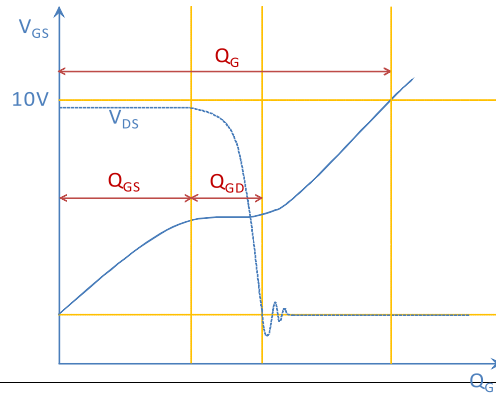
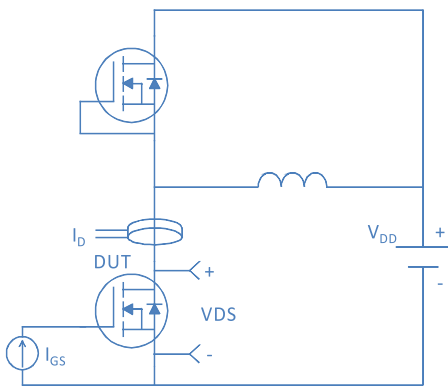
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



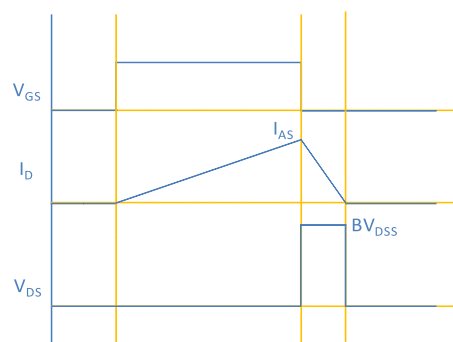
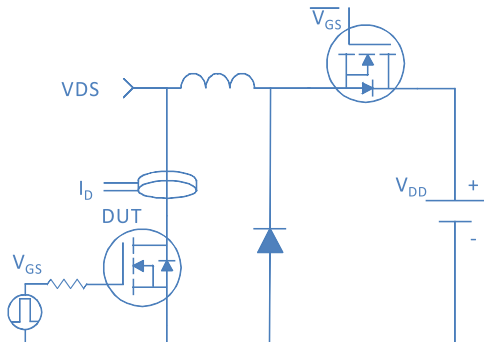
Inductive switching Test



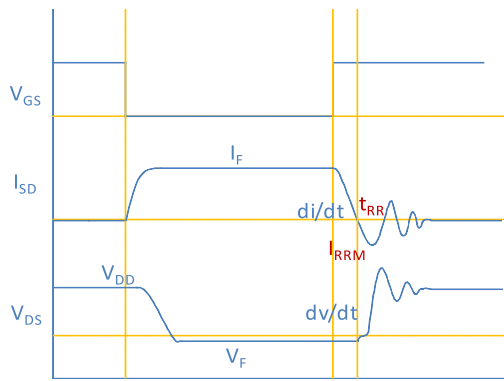
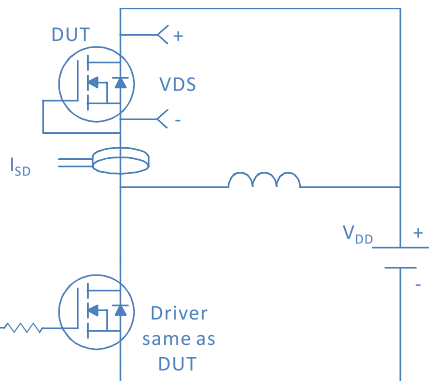
Gate Charge Test



Uclamped Inductive Switching (UIS) Test

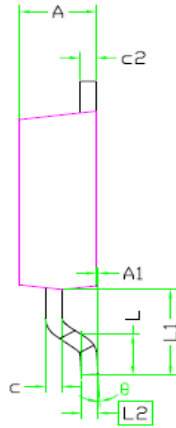
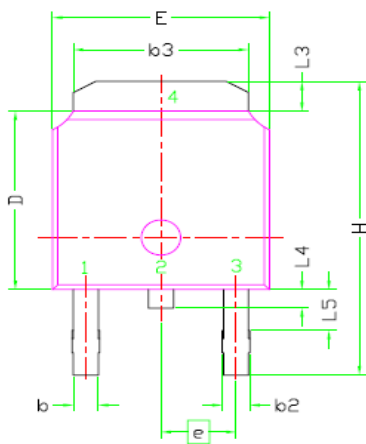


Diode Recovery Test

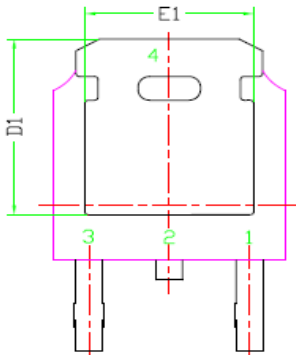


Package Outline

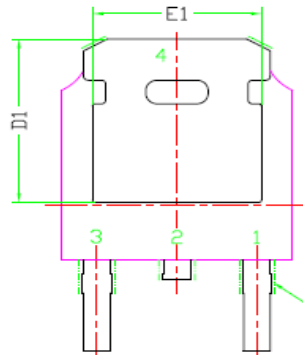
TO-252, 3 leads



SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
E	6.40	6.60	6.731
L	1.40	1.52	1.77
L1	2.743 REF		
L2	0.508 BSC		
L3	0.89	--	1.27
L4	0.64	--	1.01
L5	--	--	--
D	6.00	6.10	6.223
H	9.40	10.00	10.40
b	0.64	0.76	0.88
b2	0.77	0.84	1.14
b3	5.21	5.34	5.46
e	2.286 BSC		
A	2.20	2.30	2.38
A1	0	--	0.127
c	0.46	0.50	0.60
c2	0.46	0.50	0.58
D1	5.21	--	--
E1	4.40	--	--
θ	0°	--	10°



SINGLE ROW(NEW)



MATRIX L/F

COPPER EXPOSITION AREA